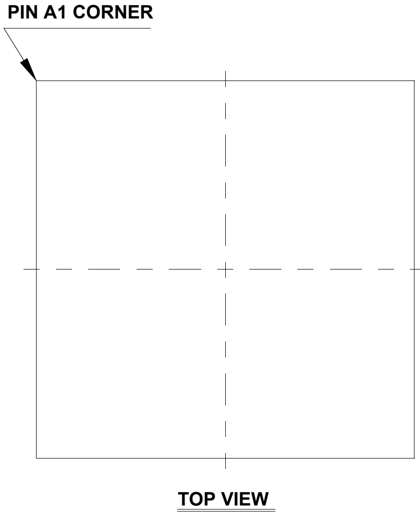
Package Outline Drawing

V172.8x8

172 THIN, FINE PITCH BALL GRID ARRAY PACKAGE

Rev 0, 12/12



		SYMBOL	COMMON DIMENSIONS		
			MIN	NOM	MAX
Package			TFBGA		
Body Size	X	E	8.000		
	Y	D	8.000		
Ball Pitch		e	0.500		
Total Thickness		A			1.200
Mold Thickness		M	0.530 Ref.		
Substrate Thickness		S	0.260 Ref.		
Ball Diameter			0.300		
Stand Off		A1	0.160	-	0.500
Ball Width		b	0.270	-	0.600
Package Edge Tolerance		aaa	0.100		
Mold Parallelism		bbb	0.100		
Coplanarity		ddd	0.080		
Ball Offset (Package)		eee	0.150		
Ball Offset (Ball)		fff	0.080		
Ball Count		n	172		
Edge Ball Center to Center	X	E1	6.500		
	Y	D1	6.500		

NOTES:

1. Dimensions are in millimeters.
2. Dimensioning and tolerancing conform to ASME Y 14.5M-1994.
3. “N” is the total number of balls.
4. Primary datum C and seating plane are defined by the spherical crowns of the contact balls.
5. Pin “A1” is marked on the top and bottom side adjacent to A1.
6. “MD” and “ME” are the number of balls in the matrix in the D and E directions respectively.